

HM50N06D-VB Datasheet

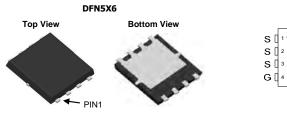
N-Channel 60 V (D-S) MOSFET

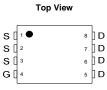
| PRODUCT SUMMARY | | | | |
|---------------------|---|----|--|--|
| V _{DS} (V) | V _{DS} (V) R _{DS(on)} (Ω) | | | |
| 60 | 0.006 at V _{GS} = 10 V | 80 | | |
| | 0.007 at V _{GS} = 4.5 V | 65 | | |

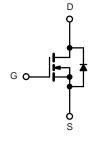
FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T_{C} = | = 25 °C, unless othe | rwise noted) | | |
|---|-------------------------|-----------------------------------|--------------------------------------|----|
| Parameter | Symbol | Limit | Unit | |
| Gate-Source Voltage | V _{GS} | ± 20 | V | |
| | T _C = 25 °C | 1- | 80 | |
| Continuous Drain Current (T _J = 175 °C) ^b | T _C = 100 °C | I _D | 65 ^a | |
| Pulsed Drain Current | I _{DM} | 100 | А | |
| Continuous Source Current (Diode Conduction) | ۱ _S | 70 ^a | | |
| Avalanche Current | I _{AS} | 50 | | |
| Single Avalanche Energy (Duty Cycle \leq 1 %) | L = 0.1 mH | E _{AS} | 125 | mJ |
| Mavimum Dawar Discinction | T _C = 25 °C | P | 136 | W |
| Maximum Power Dissipation | T _A = 25 °C | P _D — | 3 ^b , 8.3 ^{b, c} | vv |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | | | | |
|--|------------------------|---------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^a | $t \le 10 \text{ sec}$ | - R _{thJA} | 15 | 18 | | |
| Maximum Junction-to-Ambient* | Steady State | | 40 | 50 | °C/W | |
| Maximum Junction-to-Case | | R _{thJC} | 0.85 | 1.1 | | |

Notes:

a. Package limited.

c. $t \le 10$ s.

b. Surface mounted on 1" x 1" FR4 board.

| Parameter | Symbol | Test Conditions | Min. | Tun a | Max. | Unit | |
|---|---------------------|---|-------|-------------------|-------|------|--|
| | Symbol | Test conditions | wiin. | Typ. ^a | wax. | Unit | |
| Static | N N | | | | | | |
| Drain-Source Breakdown Voltage | | | 60 | | | V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 2.5 | | 4 | | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 V$, $V_{GS} = \pm 20 V$ | | | ± 100 | nA | |
| | | $V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | | | 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$ | | | 50 | μA | |
| | | $V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$ | | | 250 | | |
| On-State Drain Current ^b | I _{D(on)} | $V_{DS} = 5 V, V_{GS} = 10 V$ | 60 | | | А | |
| | | V _{GS} = 10 V, I _D = 20 A | | 0.006 | | | |
| - · | D D | V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C | 0.010 | | | Ω | |
| Drain-Source On-State Resistance ^b | R _{DS(on)} | V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C | | 0.015 | | | |
| | | V _{GS} = 4.5 V, I _D = 15 A | 0.007 | | | | |
| Forward Transconductance ^b | 9 _{fs} | V _{DS} = 15 V, I _D = 20 A | | 60 | | S | |
| Dynamic | | | | 1 | | | |
| Input Capacitance | C _{iss} | | | 2650 | | | |
| Output Capacitance | C _{oss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 470 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 225 | | | |
| Total Gate Charge ^c | Qg | | | 47 | 70 | | |
| Gate-Source Charge ^c | Q _{gs} | V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 50 A | | 10 | | nC | |
| Gate-Drain Charge ^c | Q _{gd} | | | 12 | | 1 | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 10 | 20 | | |
| Rise Time ^c | t _r | $V_{DD} = 30 \text{ V}, \text{ R}_{L} = 0.6 \Omega$ | | 15 | 25 | ns | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_a = 2.5 \Omega$ | | 35 | 50 | | |
| Fall Time ^c | t _f | Ŭ | | 20 | 30 | | |
| Source-Drain Diode Ratings and Cha | aracteristics (| $T_{\rm C} = 25 ^{\circ}{\rm C}$ | | | | | |
| Pulsed Current | I _{SM} | | | | 60 | А | |
| Diode Forward Voltage | V _{SD} | I _F = 20 A, V _{GS} = 0 V | | 1 | 1.5 | V | |
| Reverse Recovery Time | t _{rr} | I _F = 20 A, di/dt = 100 A/µs | | 45 | 100 | ns | |

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. Independent of operating temperature.

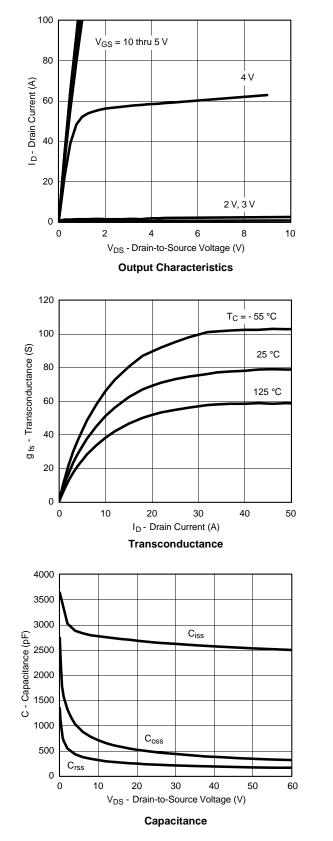
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

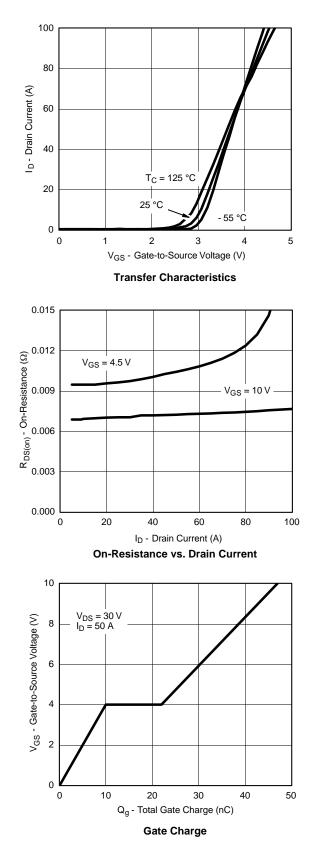
Bsemi

www.VBsemi.com



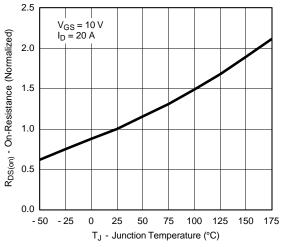
TYPICAL CHARACTERISTICS (25 °C unless noted)



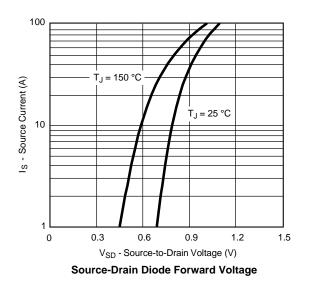




TYPICAL CHARACTERISTICS (25 °C unless noted)

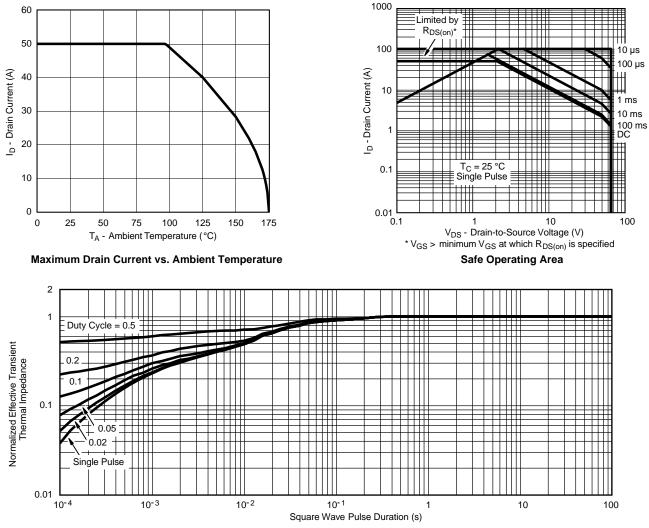


On-Resistance vs. Junction Temperature



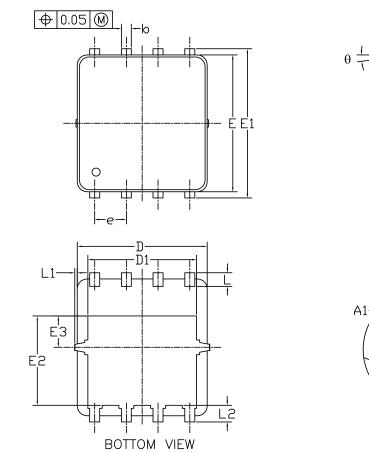


THERMAL RATINGS

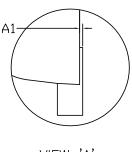


Normalized Thermal Transient Impedance, Junction-to-Case





DFN5x6_8L_EP1_P PACKAGE OUTLIN



Α

С

VIEW 'A'

<u>VIEW 'A'</u> (SCALE 5:1)

RECOMMENDED LAND PATTERN .60 -0.55 0.50 -0.77 -0.635 4.12 6.15 -1.60 + + 0.65 +|+| ŧ -11.27-0.50-

| SYMBOLS | DIMENSIONS IN MILLIMETERS | | | DIMENSIONS IN INCHES | | |
|---------|---------------------------|----------|-------|----------------------|-----------|-------|
| STNBOLS | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.85 | 0.95 | 1.00 | 0.033 | 0.037 | 0.039 |
| A1 | 0.00 | | 0.05 | 0.000 | | 0.002 |
| b | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |
| с | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| D | 5.10 | 5.20 | 5.30 | 0.201 | 0.205 | 0.209 |
| D1 | 4.25 | 4.35 | 4.45 | 0.167 | 0.171 | 0.175 |
| E | 5.45 | 5.55 | 5.65 | 0.215 | 0.219 | 0.222 |
| E1 | 5.95 | 6.05 | 6.15 | 0.234 | 0.238 | 0.242 |
| E2 | 3.525 | 3.625 | 3.725 | 0.139 | 0.143 | 0.147 |
| E3 | 1.175 | 1.275 | 1.375 | 0.046 | 0.050 | 0.054 |
| e | | 1.27 BSC | | | 0.050 BSC | |
| L | 0.45 | 0.55 | 0.65 | 0.018 | 0.022 | 0.026 |
| L1 | 0 | | 0.15 | 0 | | 0.006 |
| L2 | 0.68 REF | | | 0.027 REF | | |
| θ | 0° | | 10° | 0° | | 10° |

NOTE

UNIT: mm

 PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
CONTROLLING DIMENSION IS MILLIMETER.

CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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